



Atty. Dkt. No. 035905-0164

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: S. Brad HERNER et al.  
Title: LOW-TEMPERATURE, LOW-RESISTIVITY HEAVILY DOPED P-TYPE POLYSILICON DEPOSITION  
Appl. No.: 10/769,047  
Filing Date: 1/30/2004  
Examiner: Chen, Bret P.  
Art Unit: 1762  
Confirmation No.: 7037

**RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This communication is responsive to the Notice of Non-Compliant Amendment mailed on July 10, 2007, concerning the above-referenced patent application. Applicants resubmit herewith the updated "Amendments to the Claims" section of the Amendment filed on April 26, 2007, in compliance with 37 CFR § 1.121. Since this paper is filed within the one-month shortened statutory period, Applicants consider this paper timely filed.

Respectfully submitted,

Date 7/8/07

By Leon Radomsky

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